1.1 Scope.

This specification covers the detail requirements of CMOS monolithic analog multiplexers ADG528A and ADG529A with 8 channels and dual 4 channels, respectively. These multiplexers also feature high switching speeds, low R_{ON} and on-chip latches to facilitate microprocessor interfacing. Break-Before-Make switching is guaranteed.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number[1]
−1	ADG528AT(X)/883B
−2	ADG529AT(X)/883B

NOTE
[1]To complete the part number substitute the package identifier as shown in paragraph 1.2.3.

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
Q	Q-18	18-Pin Cerdip
E	E-20A	20-Terminal LCC

1.3 Absolute Maximum Ratings. (T_A = +25°C)

V+ to V− . . . . 44 V
V+ to GND . . . . 25 V
V− to GND . . . . −25 V
Analog Inputs
  Voltage at S, D . . . . V− to V+
  Continuous Current, S or D . . . . 30 mA
  Pulsed Current S or D
    1 ms Duration, 10% Duty Cycle . . . . 70 mA
Digital Inputs
  Voltages at IN . . . . V− −4 V to V+ +4 V or
                                                            20 mA, Whichever Occurs First
Power Dissipation (Package)
  Up to +75°C . . . . 470 mW/°C
  Derates above +75°C by . . . . 6 mW°C
Operating Temperature . . . . −55°C to +125°C
Storage Temperature Range . . . . −65°C to +150°C
Lead Temperature (Soldering 10 sec) . . . . +300°C
Junction Temperature (T_J) . . . . +175°C

1.5 Thermal Characteristics.

Thermal Resistance θ_{JC} = 35°C/W for Q-18 and E-20A
                    θ_{JA} = 120°C/W for Q-18 and E-20A

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SWITCHES & MULTIPLEXERS

ADG528A/ADG529A — SPECIFICATIONS

Table 1.

Test	Symbol	Device	Design Limit T_{min}–T_{max}	Sub Group 1	Sub Group 2, 3	Test Conditions[1]/Comments	Units
Switch ON Resistance	R_{DS}	–1, 2	400	300	400	$V_S = +10$ V; $V_S = -10$ V; $I_{DS} = 1$ mA; Test Circuit 1	Ω max
		–1, 2	600	450	600	V+ = +10.8 V; V– = –10.8 V; Test Circuit 1	Ω max
Source OFF Leakage Current	I_S (OFF)	–1, 2	50	1	50	V+ = +16.5 V; V– = –16.5 V; Test Circuit 2	±nA max
Drain OFF Leakage Current	I_D (OFF)	–1	200	1	200	$V_D = V_S = \pm 10$ V; V+ = +16.5 V; V– = –16.5 V; Test Circuit 3	±nA max
		–2	100	1	100		
Channel ON Leakage Current	I_D (ON)	–1	200	1	200	$V_D = V_S = \pm 10$ V; V+ = +16.5 V; V– = –16.5 V; Test Circuit 4	±nA max
		–2	100	1	100		
Differential OFF Output Leakage	I_{DIFF}	–2	25		25	V1 = ±10 V; V2 = ±10 V; Test Circuit 5	±nA max
Digital Input High Voltage	V_{INH}	–1, 2	2.4	2.4	2.4		V min
Digital Input Low Voltage	V_{INL}	–1, 2	0.8	0.8	0.8		V max
High Level Input Current	I_{INH}	–1, 2	1	1	1	V+ = +16.5 V; V– = –16.5 V; V_{IN} = +16.5 V	±μA max
Low Level Input Current	I_{INL}	–1, 2	1	1	1	V+ = +16.5 V; V– = –16.5 V; V_{IN} = 0 V	±μA max
Supply Current	$+I_{CC}$	–1, 2	1.5	1.5	1.5	V+ = +16.5 V; V– = –16.5 V; V_{INH} = 2.4 V; V_{INL} = 0.8 V	mA max
	$-I_{CC}$	–1, 2	0.2	0.2	0.2		mA max
Subgroup 9, 10, 11 $t_{TRANSITION}$	t_{TRANS}	–1, 2	400			V1 = ±10 V, V2 = ±10 V; Test Circuit 6	ns max
Subgroup 9, 10, 11 t_{ON} (ENABLE, $\overline{WRITE}$)	t_{ON} (EN, $\overline{WR}$)	–1, 2	400			Test Circuit 7a, 7b, 7c	ns max
t_{OFF} (ENABLE, $\overline{RESET}$)	t_{OFF} (EN, $\overline{RS}$)	–1, 2	400				
Subgroup 12 Off Isolation	V_{ISO}	–1, 2	50			$R_L = 1$ kΩ; $C_L = 12$ pF; Test Circuit 8 $V_{IN} = 10$ V pk–pk, f = 100 kHz; $T_A = +25$°C	dB min
Subgroup 13 Crosstalk between Channels	V_{CT}	–1, 2	60			$V_S = 20$ V pk–pk; $R_L = 1$ kΩ; $C_L = 12$ pF; $T_A = +25$°C; Test Circuit 9	dB min
Subgroup 14 Charge Injection	Q_{INJ}	–1, 2	50			Test Circuit 10	pC max
Digital Input Capacitance	C_{IN}	–1, 2	20				pF max
Source Capacitance, OFF	C_S (OFF)	–1, 2	20				pF max
Drain Capacitance, OFF	C_D (OFF)	–1	100				pF max
		–2	50				pF max

NOTE: DUAL SUPPLY OPERATION – ±15 V
[1]Unless otherwise noted V+ = +15 V; V– = –15 V.

Table 2.

Test	Symbol	Device	Design Limit T_{min}–T_{max}	Sub Group 1	Sub Group 2, 3	Test Conditions[1]/Comments	Units
Switch ON Resistance	R_{DS}	–1, 2	1000	700	1000	V_D = +10 V; V_S = 0 V; I_{DS} = 0.5 mA $V+$ = +10.8 V; $V-$ = 0 V; Test Circuit 1	Ω max
Source OFF Leakage Current	I_S (OFF)	–1, 2	50	1	50	$V+$ = +16.5 V; $V-$ = 0 V; Test Circuit 2	±nA max
Drain OFF Leakage Current	I_D (OFF)	–1	200	1	200	$V+$ = +16.5 V; $V-$ = 0 V $V1$ = +10 V/0 V; $V2$ = 0 V/+10 V; Test Circuit 3	±nA max
		–2	100	1	100		
Channel ON Leakage Current	I_D (ON)	–1	200	1	200	$V+$ = +16.5 V; $V-$ = 0 V; $V1$ = +10 V/0 V; $V2$ = 0 V/+10 V Test Circuit 4	±nA max
		–2	100	1	100		
Differential OFF Output Leakage	I_{DIFF}	–2	25		25	$V+$ = +16.5 V; $V-$ = 0 V $V1$ = +10 V/0 V; $V2$ = 0 V/+10 V Test Circuit 5	±nA max
Digital Input High Voltage	V_{INH}	–1, 2	2.4	2.4	2.4		V min
Digital Input Low Voltage	V_{INL}	–1, 2	0.8	0.8	0.8		V max
High Level Input Current	I_{INH}	–1, 2	1	1	1	$V+$ = +16.5 V; $V-$ = 0 V; V_{IN} = +16.5 V	±µA max
Low Level Input Current	I_{INL}	–1, 2	1	1	1	$V+$ = +16.5 V; $V-$ = 0 V; V_{IN} = 0 V	±µA max
Supply Current	+I_{CC}	–1, 2	1.5	1.5	1.5	$V+$ = +16.5 V; $V-$ = 0 V; V_{INH} = 2.4 V; V_{INL} = 0.8 V	mA max
Subgroup 9, 10, 11 $t_{TRANSITION}$	t_{TRANS}	–1, 2	600			$V1$ = 10 V/0 V; $V2$ = 0 V/10 V; Test Circuit 6	ns max
Subgroup 9, 10, 11 t_{ON} (ENABLE, $\overline{WRITE}$)	t_{ON} (EN, $\overline{WR}$)	–1, 2	600			Test Circuit 7a, 7b, 7c	ns max
t_{OFF} (ENABLE, $\overline{RESET}$)	t_{OFF} (EN, $\overline{RS}$)	–1, 2	600				
Subgroup 12 Off Isolation	V_{ISO}	–1, 2	50				dB min
Subgroup 13 Crosstalk between Channels	V_{CT}	–1, 2	60				dB min
Subgroup 14 Charge Injection	Q_{INJ}	–1, 2	50				pC max
Digital Input Capacitance	C_{IN}	–1, 2	20				pF max
Source Capacitance, OFF	C_S (OFF)	–1, 2	20				pF max
Drain Capacitance, OFF	C_D (OFF)	–1	100				pF max
		–2	50				pF max

NOTE: SINGLE SUPPLY OPERATION – +15 V
[1]Unless otherwise noted $V+$ = +15 V; $V-$ = 0 V.

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SWITCHES & MULTIPLEXERS

ADG528A/ADG529A

3.2.1 Functional Block Diagram and Terminal Assignments.

ADG528A

S1 — D
S8
$\overline{WR}$ — DECODER/LATCHES
A0 A1 A2 EN $\overline{RS}$

ADG529A

S1A — DA
S4A
S1B — DB
S4B
$\overline{WR}$ — DECODER/LATCHES
A0 A1 EN $\overline{RS}$
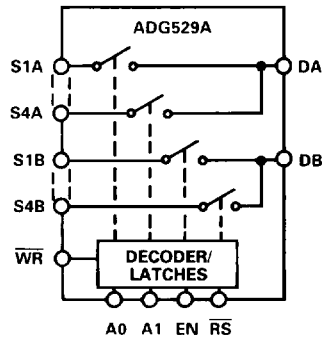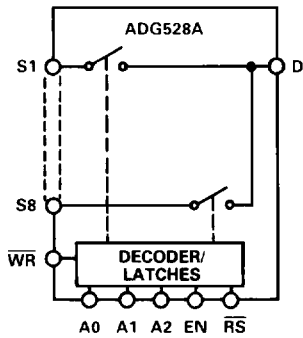
Pin Assignments

DIP Package

ADG528A
TOP VIEW
(Not to Scale)

$\overline{WR}$	1	18	$\overline{RS}$
A_0	2	17	A_1
EN	3	16	A_2
V_{SS}	4	15	GND
S1	5	14	V_{DD}
S2	6	13	S5
S3	7	12	S6
S4	8	11	S7
D	9	10	S8

DIP Package

ADG529A
TOP VIEW
(Not to Scale)

$\overline{WR}$	1	18	$\overline{RS}$
A_0	2	17	A_1
EN	3	16	GND
V_{SS}	4	15	V_{DD}
S1A	5	14	S1B
S2A	6	13	S2B
S3A	7	12	S3B
S4A	8	11	S4B
DA	9	10	DB

LCCC

ADG528A
TOP VIEW
(Not to Scale)

A0 $\overline{WR}$ NC $\overline{RS}$ A1
3 2 1 20 19

EN 4 — 18 A2
V_{SS} 5 — 17 GND
S1 6 — 16 V_{DD}
S2 7 — 15 S5
S3 8 — 14 S6

9 10 11 12 13
S4 D NC S8 S7   NC = NO CONNECT

LCCC

ADG529A
TOP VIEW
(Not to Scale)

A0 $\overline{WR}$ NC $\overline{RS}$ A1
3 2 1 20 19

EN 4 — 18 GND
V_{SS} 5 — 17 V_{DD}
S1A 6 — 16 S1B
S2A 7 — 15 S2B
S3A 8 — 14 S3B

9 10 11 12 13
S4A DA NC DB S4B   NC = NO CONNECT

MIL-STD-883 Test Requirements	Subgroups (See Table 1)
Interim Electrical Parameters (Pre-Burn-In) Method 5004	1
Final Electrical Parameters, Method 5004	1*, 2, 3, 9
Group A Electrical Parameters, Method 5005	1, 2, 3, 9, 10**, 11**
Group C End Point Electrical Parameters, Method 5005	1

NOTES
*Indicates PDA applies to Subgroup 1.
**Subgroups 10 & 11, if not tested, shall be guaranteed to the limits in the data sheet.

TRUTH TABLES

Table 3. ADG528A Truth Table

A2	A1	A0	EN	$\overline{WR}$	$\overline{RS}$	ON SWITCH PAIR
X	X	X	X	⌐	1	Retains Previous Switch Condition
X	X	X	X	X	0	NONE (Address and Enable Latches Cleared)
X	X	X	0	0	1	NONE
0	0	0	1	0	1	1
0	0	1	1	0	1	2
0	1	0	1	0	1	3
0	1	1	1	0	1	4
1	0	0	1	0	1	5
1	0	1	1	0	1	6
1	1	0	1	0	1	7
1	1	1	1	0	1	8

X = Don't Care

Table 4. ADG529A Truth Table

A1	A0	EN	$\overline{WR}$	$\overline{RS}$	ON SWITCH PAIR
X	X	X	⌐	1	Retains Previous Switch Condition
X	X	X	X	0	NONE (Address and Enable Latches Cleared)
X	X	0	0	1	NONE
0	0	1	0	1	1
0	1	1	0	1	2
1	0	1	0	1	3
1	1	1	0	1	4

X = Don't Care

3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (82).

SWITCHES & MULTIPLEXERS
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ADG528A/ADG529A

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).
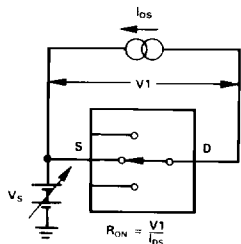
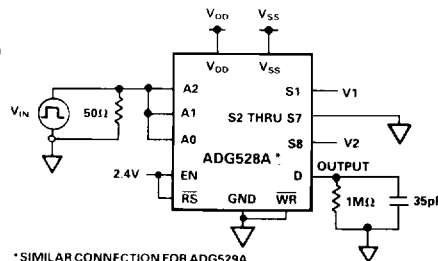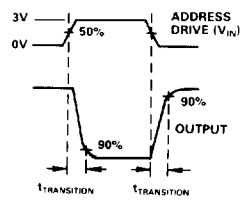Test Circuit 1
R_{ON}
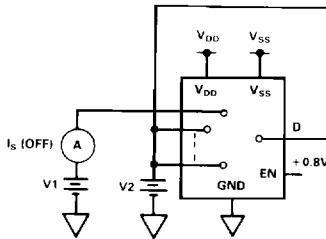
Test Circuit 2
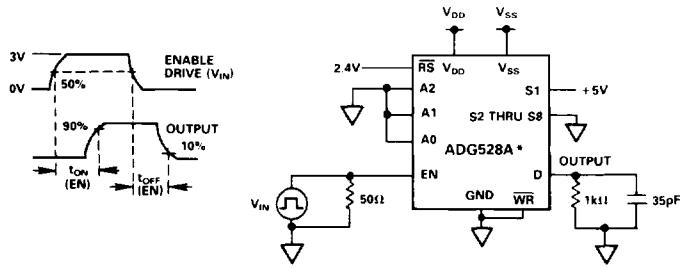I_S (OFF)
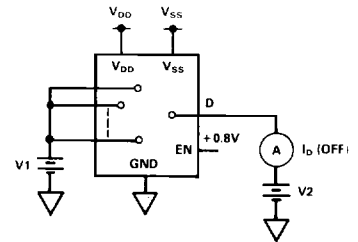
Test Circuit 3
I_D (OFF)
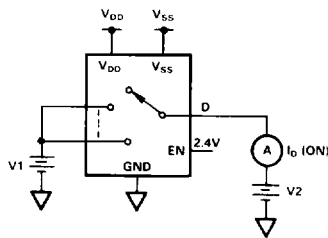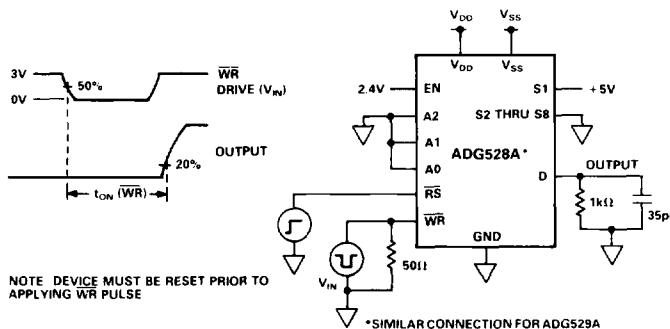

Test Circuit 4
I_D (ON)

Test Circuit 5
I_{DIFF}

Test Circuit 6
Switching Time of Multiplexer, $t_{TRANSITION}$

Test Circuit 7a
Enable Delay, t_{ON} (EN), t_{OFF} (EN)

NOTE DEVICE MUST BE RESET PRIOR TO
APPLYING $\overline{WR}$ PULSE

Test Circuit 7b
Write Turn-On Time, t_{ON} $(\overline{WR})$
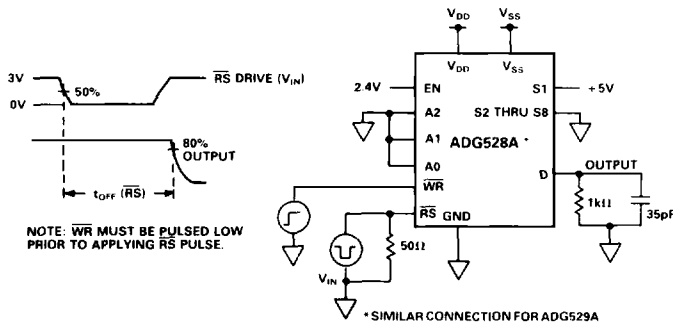
NOTE: $\overline{WR}$ MUST BE PULSED LOW
PRIOR TO APPLYING $\overline{RS}$ PULSE.
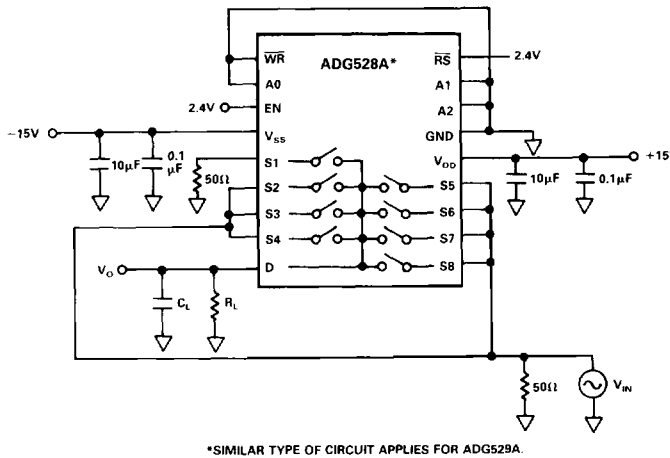
Test Circuit 7c
Reset Turn-Off Time, t_{OFF} $(\overline{RS})$

ADG528A/ADG529A

*SIMILAR TYPE OF CIRCUIT APPLIES FOR ADG529A.
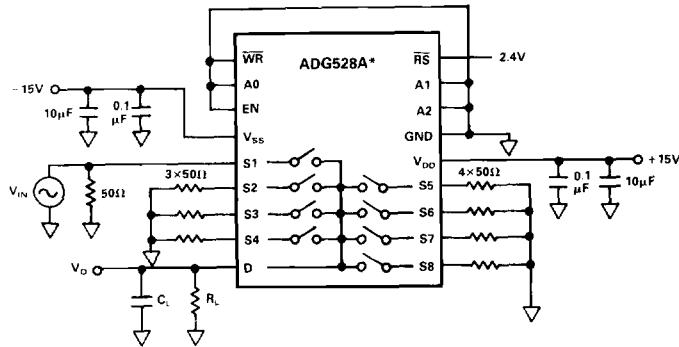
Test Circuit 8
OFF Isolation

*SIMILAR TYPE OF CIRCUIT APPLIES FOR ADG529A.

Test Circuit 9
Crosstalk Between Channels

$Q_{INJ} = CL \times \Delta V_O$

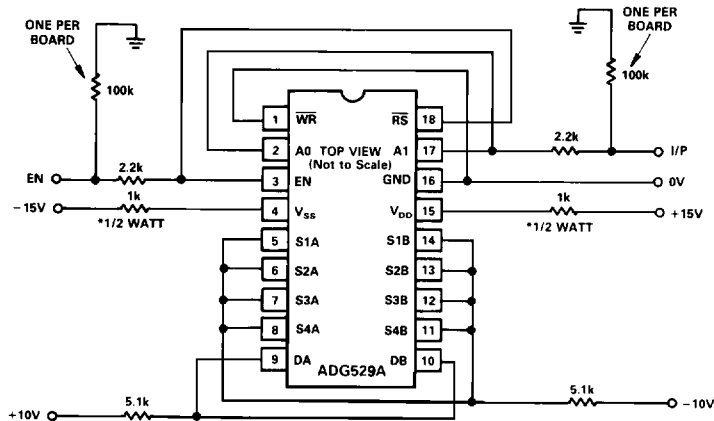*SIMILAR CONNECTION FOR ADG529A
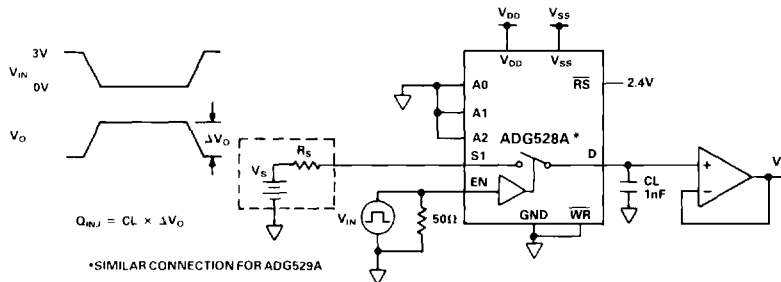
Test Circuit 10
Charge Injection
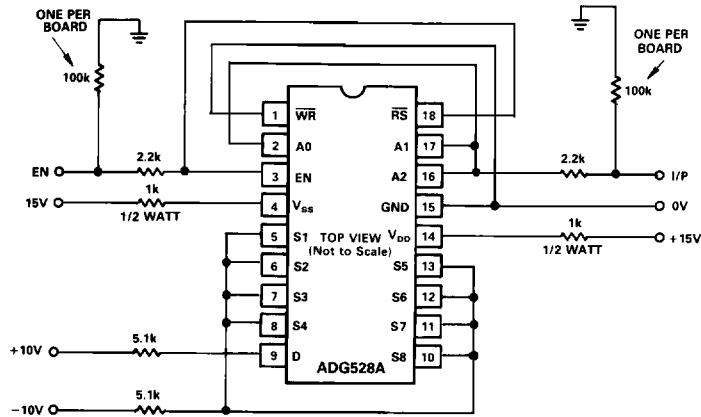
NOTES
I/P = +15V; WR = GND; EN = 0V; RS = 0V
MAX CURRENT RATINGS
  MAX I_{DD} = 2mA NOT THE ABSOLUTE MAX RATINGS
  MAX I_{SS} = 2mA
MAX CONTINUOUS CURRENT S OR D = 20mA
N.B. NOTE POWER RATINGS OF 1k RESISTORS

ADG528A Static Burn-In Board

NOTES
I/P = +15V; WR = GND; EN = 0V; RS = 0V
MAX CURRENT RATINGS
  MAX I_{DD} = 2mA NOT THE ABSOLUTE MAX RATINGS
  MAX I_{SS} = 2mA
*N.B. NOTE POWER RATING OF 1k RESISTORS
MAX CONTINUOUS CURRENT S OR D = 20mA

ADG529A Static Burn-In Board

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